AIP1640 LED Control Dedicated Circuit Product Introduction

1. Overview

It is a dedicated circuit for LED driving control (LED Display) with integrated MCU digital ports, data latch, LED high voltage driver and other circuits. This product has excellent performance and reliable quality. It is mainly applied to display drive of small household appliances and electronic scales.

Features:

- CMOS process
- Brightness adjustment circuit (duty cycle 8 levels adjustable)
- Two-wire serial interface (CLK, DIN)
- Oscillation mode: Built-in RC oscillation (450KHz+5%)
- Built-in power-on reset circuit
- Built-in automatic blanking circuit
- Display mode (8 segments × 16 bits), support common cathode digital tube output
- Package: SOP28

2. Functional Diagram and Pin Description

Pin Diagram

	_	A STATE OF THE STA		ST
1		GRID12	GRID11	28
2		GRID13	GRID10	27
3		GRID14	GRID9	20
4		GRID15	GRID8	25
5		GRID16	GRID7	24
6		VSS	GRID6	23
7		DIN	GRID5	22
8		SCLK	GRID4	21
9		SEG1	GRID3	20
10		SEG2	GRID2	19
11		SEG3	GRID1	18
12		SEG4	VDD	17
13		SEG5	SEG8	16
14		SEG6	SEG7	15
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Pin Description And Structure Schematic

Pin	Name	Symbol	Description
1	Output(bits)	GRID12	Bits output, N tube Open drain output
2	Output(bits)	GRID13	Bits output, N tube Open drain output
3	Output(bits)	GRID14	Bits output, N tube

			Open drain output
4	Output(bits)	GRID15	Bits output, N tube
			Open drain output
5	Output(bits)	GRID16	Bits output, N tube
			Open drain output
6	Logically	VSS	Connect to GMD
7	Data input	DIN	Serial data input,
			input data changes
			at Low level of
			SCLK
			, transmitted at
			high level of SCLK
8	Clock input	SCLK	Enter data on the
			rising edge
9	Output	SEG1	Segment output, P
	(segment)		tube open drain
			output

10	Output	SEG2	Segment output, P
	-	3202	
	(segment)		tube open drain
			output
11	Output	SEG3	Segment output, P
	(segment)		tube open drain
			output
12	Output	SEG4	Segment output, P
	(segment)		tube open drain
			output
13	Output	SEG5	Segment output, P
	(segment)		tube open drain
			output
14	Output	SEG6	Segment output, P
	(segment)		tube open drain
			output
15	Output	SEG7	Segment output, P
	(segment)		tube open drain
			output

16	Output (segment)	SEG8	Segment output, P tube open drain output
17	Logic power supply	VDD	5V±10%
18	Output(bits)	GRID1	Bits output, N tube Open drain output
19	Output(bits)	GRID2	Bits output, N tube Open drain output
20	Output(bits)	GRID3	Bits output, N tube Open drain output
21	Output(bits)	GRID4	Bits output, N tube Open drain output
22	Output(bits)	GRID5	Bits output, N tube Open drain output

23	Output(bits)	GRID6	Bits output, N tube Open drain output
24	Output(bits)	GRID7	Bits output, N tube Open drain output
25	Output(bits)	GRID8	Bits output, N tube Open drain output
26	Output(bits)	GRID9	Bits output, N tube Open drain output
27	Output(bits)	GRID10	Bits output, N tube Open drain output
28	Output(bits)	GRID11	Bits output, N tube Open drain output

3. Electrical Property
Limit parameters (Tamb=25°C, Vss = 0V unless otherwise specified)

Parameter	Symbol	Condition	Rated value	Unit
Name				
Power supply	VCC		-0.5 ~ +7.0	V
voltage				
Logic input	VI1		-0.5~VDD+0.5	V
voltage				
LED Seg Drive	IO1		-50	mA
Output Current				
LED Grid drive	IO2		+200	mA
output current				
Power loss	PD		400	mW
Working	Topt		-40~+85	°C
temperature				
Storage	Tstg		-65~+150	°C
temperature				
Welding	TL	10s	250	°C
temperature				

Recommended Conditions (Ta = $-40 \sim +85$ °C, Vss = 0V)

Parameter	Symbol	Minimum	Typical	Maximum	Unit
name					
Logic supply	VDD		5		٧
voltage					
High level	VIH	0.7VDD	-	VDD	٧
input voltage					
	VIL	0	-	0.3VDD	V
Low level					
input voltage					

Electrical Characteristics

Electrical Characteristics (Ta=-40~+85°C, VDD = 4.5V~5.5 V, GND=0V)

Parameter name	Symbol	Test Condition	Minimum	Typical	Maximum	Unit
High level	Ioh1	GRID1~GRID1	-20	-25	-40	mA
output		6, Vo =				
current		vdd-2V				
	Ioh2	GRID1~GRID1	-20	-30	-50	mA
		6, Vo =				
		vdd-3V				
Low level	IOL1	SEG1~SEG8	80	140	-	mA
output		Vo=0.3V				
current						
Low level	Idout	VO = 0.4V,	4	-	-	mA
output		dout				
current						
High level	Itolsg	VO = VDD -	-	-	5	%
output		3V, GRID1 \sim				
current		GRID16 -				
tolerance						
Input	II	VI = VDD / VSS	-	-	±1	μΑ
Current						

High level	VIH	CLK, DIN	0.7VDD	-		V
input						
voltage						
	VIL	CLK, DIN	-	-	0.3VDD	V
Low level						
input						
voltage						
Hysteretic	VH	CLK, DIN	-	0.35	-	V
voltage						
Dynamic	IDDdyn	No load,	-	-	5	MA
current		display off				
loss						

Switch Characteristics (unless otherwise specified, Tamb = -40 \sim +85 $^{\circ}$ C, VDD= 4.5 \sim 5.5V)

Parameter	Symbol	Test	Minimum	Typical	Maximum	Unit
Name		Condition				
Oscillating	Fosc		-	450	-	KHz
frequency						

Transmission	tPLZ	$CLK \to$	-	-	300	ns
delay time		DIO CL =				
		15pF, RL				
		= 10K Ω				
	tPZL		ı	ı	100	
Rise Time	TTZH 1	GRID1 \sim	1	1	2	μs
		GRID16 CL				
		=300p F				
	TTZH 2	SEG1 \sim	1	-	0.5	μs
		SEG8 CL				
		=300p F				
Fall time	TTHZ	CL =	-	-	120	μs
		300pF,				
		Segn,				
		Gridn				
Maximum	Fmax	Duty Cycle	1	-	-	MHZ
clock		50%				
frequency						
Input	CI	-	-	-	15	pF
capacitance						

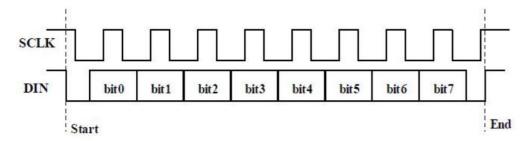
Clock Characteristics (Tamb=-40 \sim +85 $^{\circ}$ C, VDD= 4.5 \sim 5.5V unless otherwise specified)

Parameter	Symbol	Test	Minimum	Typical	Maximum	Unit
Name		Condition				
Clock Pulse	PWCLK	-	400	-	-	ns
Width						
Strobe	PWSTB	-	1	-	-	μs
Width						
Data	tSETUP	-	100	-	-	ns
Building-up						
Time						
Data	tHOLD	-	100	ı	-	ns
Retention						
Time						
Waiting	tWAIT	CLK↑→CLK↓	1	-	-	μs
Time						

Interface Description

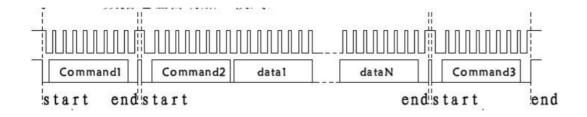
Microprocessor data communicates via the AIP1640 and two-wire bus interface. When CLK is high level and inputting data, the signal on DIN must be remained unchanged. Only when the clock signal on CLK is low level, the signal on DIN can be changed. The input of data is always low bit first and the high bit is transmitted later. The start condition of data input is when CLK is high level, DIN changes from low level to high level; the end condition is when CLK is high level, DIN changes from low level to high level.

The instruction data transmission process is as follows:



Instruction Data Transmission Format

Write SRAM data address automatically added 1 mode:



Automatic address write data format

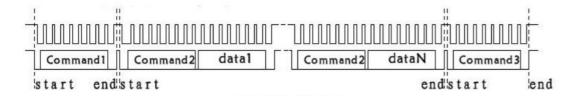
Command1: Setting data

Command2: Setting address

Data1~N: Transfer display data

Command3: Control display

Write SRAM data fixed address mode:



Fixed address write data format

Command1: Setting data

Command2: Setting address

Data1~N: Transfer display data

Command3: Control display

Data instruction

Instructions are used to set the display mode and the status of the LED driver. The first byte entered by DIN is used as an instruction after the instruction START is valid. After decoding, the B7 and B6 bits are taken to distinguish different instructions.

B7 0	B6	Introduction Data command setting Display control command setting
1	0	Display control command secting
1	1	Address command setting

If END is valid when an instruction or data transfers, the serial communication is initialized and the instruction or data being transferred is invalid (the previous transmitted instruction or data remains valid).

Data command settings:

В7	В6	B 5	B4	В3	B2	B1	В0	Description
0	1	Tunala			0			Address
0	1	Irrele	vant		1	Irrele	evant	automatically added
0	1	item,	fill	0		item,	fill in	Fixed address
0	1	in 0		1		0		Universal mode
0	1		0					Test mode

Address command setting

В7	В6	B5	B4	В3	B2	B1	В0	Display address
1	1	1	4	0	0	0	0	00H
1	1	Irrele	vant	0	0	0	1	01H
1	1	item.	fill in	0	0	1	0	02H
1	1]		0	0	1	1	03H
1	1	0		0	1	0	0	04H
1	1			0	1	0	1	05H
1	1				1	1	0	06H
1	1				1	1	1	07H
1	1			1	0	0	0	08H
1	1			1	0	0	1	09H
1	1			1	0	1	0	0AH
1	1			1	0	1	1	0BH
1	1			1	1	0	0	0CH
1	1				1	0	1	0DH
1	1			1	1	1	0	0EH
1	1			1	1	1	1	0FH

Display address command settings

At power-on, the address is set to 00H by default.

The correspondent relationship between display data and chip pins and display addresses is shown in the following table:

	SEG1	SEG2	SEG3	SEG4	SEG5	SEG6	SEG7	SEG8				
	B0	B1	B2	В3	B4	B5	В6	В7				
GRID1	Display address 00H											
GRID2		Display address 01H										
GRID3			2H	dress 02	play ad	Dis						
GRID4			ВН	dress 03	splay ad	Dis						
GRID5			Н	dress 04	play ad	Dis						
GRID6			Н	dress 05	splay ad	Dis						
GRID7			Н	dress 06	play ad	Dis						
GRID8			'H	dress 07	play ad	Dis						
GRID9			ВН	dress 08	play ad	Dis						
GRID10			Н	dress 09	play ad	Dis						
GRID11			М	dress OA	play ad	Dis						
GRID12			ВН	dress OE	play ad	Dis						
GRID13			CH	dress OC	play ad	Dis						
GRID14		Display address 0DH										
GRID15			Н	dress 0E	play ad	Dis						
GRID16			Н	dress OF	splay ad	Dis						

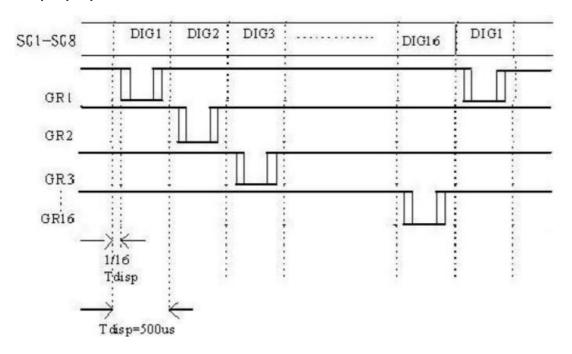
The correspondent relationship between display data, address, and chip pins

Display control

MSB	}						LSE	3	
В7	В6	B5	B4	B3	B2	B1	В0	Fuction	Description
-	0			•	^	_	0		Set pulse width 1/16
1	0	Irre	lev	1	0	0	0		Set pulse width 2/16
1	0			1	0	0	1		Set pulse width 4/16
1	0			1	0	1	0	Duightmass	Set pulse width 10/16
1	0	ant		1	0	1	1	Brightness	· · · · · · · · · · · · · · · · · · ·
1	0			1	1	0	0	setting	Set pulse width 11/16
1	0	iter	n,	1	1	0	1		Set pulse width 12/16
1	0		•	1	1	1	0		Set pulse width 13/16
1	0	fill i	n 0	1	1	1	1	Display switch	Set pulse width 14/16
1	0			0	X	X	X	setting	Display on
1	0			1	X	X	X		Display off

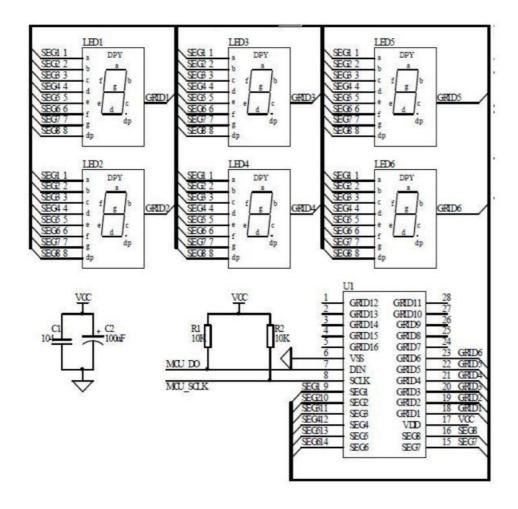
Display mode control instruction

Display cycle



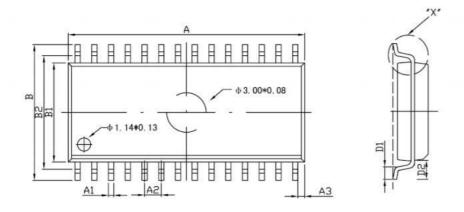
Typical application diagram and instructions

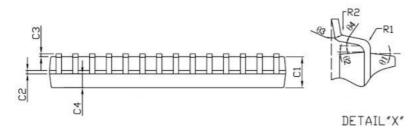
The digital tube connected in the circuit diagram is a common cathode digital tube:



Package size and outline drawing

SOP28 outline drawing and package size





Label	Minimum	Maximum	Label	Minimum	Maximum	
Α	17.83	18.03	C4	1	.043TYP	
A1	0.406	S4TYP	D1	0.70	0,90	
A2	1.27	7TYP	D2	1.395TYP		
A3	0,5	1TYP	R1	0.508TYP		
В	9,90	10,50	R2	0.508TYP		
B1	7,42	7,62	θ1	7	° TYP	
B2	8.8	TYP	θ2	5	° TYP	
C1	2.24	2,44	θ3	4° TYP		
C2	0,204	0.33	θ4	1	0° TYP	
C3	0.10	0.25		•		

Declarations and Precautions:

The name and content of toxic and hazardous substances or elements in the product

Component	Toxic o	Toxic or harmful substances or elements								
	Lead (Pb)	Mercu ry (Hg)	Cadmium (Cd)	sixth-order chromium (Cr(VI))		Polybrominated biphenyl (PBBs)	Polybro minate d biphe nyl Ethers (PBDEs)			
Lead Frame	0	0	0	0	0		0			
Sealing Gum	0	0	0	0	0		0			
Chip	0	0	0	0	0		0			
Inner Lead	0	0	0	0	0		0			
Loading Glue	0	0	0	0	0		0			
Description	elei	o: indicates that the content of the toxic or hazardous substance or element is less than the SJ/T11363-2006 standard detection limit. ×: indicates that the content of the toxic or hazardous substance or element exceeds the limit of SJ/T11363-2006 standard requirements.								

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